

ABSTRACT

DIE BOND HEAD APPARATUS WITH DIE HOLDER MOTION TABLE

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A die bond head apparatus has a die bond head body coupled to a die bond head motion table, a die holder motion table mounted on the die bond head body and a die holder which is operative in use to secure a semiconductor die to a substrate. The die holder is positionable by the die holder motion table independently of the die bond head motion table.

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[FIG. 1]